

CD4001B, CD4002B, CD4025B Types

CMOS NOR Gates

High-Voltage Types (20-Volt Rating)

Quad 2 Input – CD4001B

Dual 4 Input – CD4002B

Triple 3 Input – CD4025B

■ CD4001B, CD4002B, and CD4025B NOR gates provide the system designer with direct implementation of the NOR function and supplement the existing family of CMOS gates. All inputs and outputs are buffered.

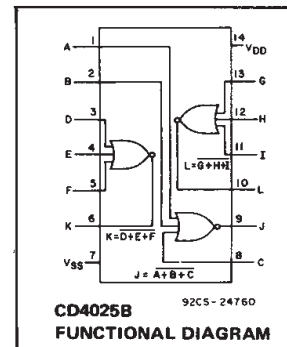
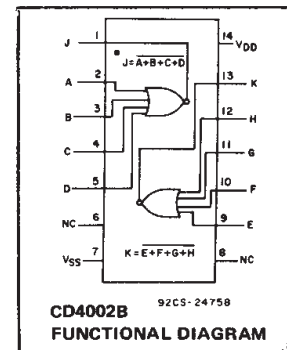
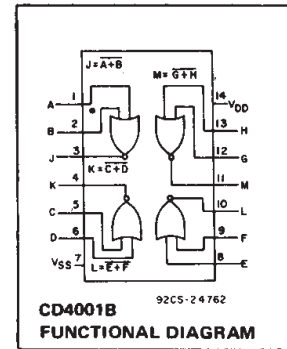
The CD4001B, CD4002B, and CD4025B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

Features:

- Propagation delay time = 60 ns (typ.) at $C_L = 50$ pF, $V_{DD} = 10$ V
- Buffered inputs and outputs
- Standardized symmetrical output characteristics
- 100% tested for maximum quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 μ A at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package temperature range):
 - 1 V at $V_{DD} = 5$ V
 - 2 V at $V_{DD} = 10$ V
 - 2.5 V at $V_{DD} = 15$ V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of "B" Series CMOS Devices"

STATIC ELECTRICAL CHARACTERISTICS

| CHARACTER- ISTIC | CONDITIONS | | | LIMITS AT INDICATED TEMPERATURES (°C) | | | | | | | UNITS |
|--|--------------|-----------------|-----------------|---------------------------------------|-----------|---------|---------|-------|---------------|-----------|---------|
| | V_O (V) | V_{IN} (V) | V_{DD} (V) | +25 | | | | | | | |
| | | | | -55 | -40 | +85 | +125 | Min. | Typ. | Max. | |
| Quiescent Device Current, I_{DD} Max. | – | 0,5 | 5 | 0,25 | 0,25 | 7,5 | 7,5 | – | 0,01 | 0,25 | μ A |
| | – | 0,10 | 10 | 0,5 | 0,5 | 15 | 15 | – | 0,01 | 0,5 | |
| | – | 0,15 | 15 | 1 | 1 | 30 | 30 | – | 0,01 | 1 | |
| | – | 0,20 | 20 | 5 | 5 | 150 | 150 | – | 0,02 | 5 | |
| Output Low (Sink) Current I_{OL} Min. | 0,4 | 0,5 | 5 | 0,64 | 0,61 | 0,42 | 0,36 | 0,51 | 1 | – | mA |
| | 0,5 | 0,10 | 10 | 1,6 | 1,5 | 1,1 | 0,9 | 1,3 | 2,6 | – | |
| | 1,5 | 0,15 | 15 | 4,2 | 4 | 2,8 | 2,4 | 3,4 | 6,8 | – | |
| | – | – | – | – | – | – | – | – | – | – | |
| Output High (Source) Current, I_{OH} Min. | 4,6 | 0,5 | 5 | -0,64 | -0,61 | -0,42 | -0,36 | -0,51 | -1 | – | mA |
| | 2,5 | 0,5 | 5 | -2 | -1,8 | -1,3 | -1,15 | -1,6 | -3,2 | – | |
| | 9,5 | 0,10 | 10 | -1,6 | -1,5 | -1,1 | -0,9 | -1,3 | -2,6 | – | |
| | 13,5 | 0,15 | 15 | -4,2 | -4 | -2,8 | -2,4 | -3,4 | -6,8 | – | |
| Output Voltage: Low-Level, V_{OL} Max. | – | 0,5 | 5 | 0,05 | | | | – | 0 | 0,05 | V |
| | – | 0,10 | 10 | 0,05 | | | | – | 0 | 0,05 | |
| | – | 0,15 | 15 | 0,05 | | | | – | 0 | 0,05 | |
| Output Voltage: High-Level, V_{OH} Min. | – | 0,5 | 5 | 4,95 | | | | 4,95 | 5 | – | V |
| | – | 0,10 | 10 | 9,95 | | | | 9,95 | 10 | – | |
| | – | 0,15 | 15 | 14,95 | | | | 14,95 | 15 | – | |
| Input Low Voltage, V_{IL} Max. | 0,5,4,5 | – | 5 | 1,5 | | | | – | – | 1,5 | V |
| | 1,9 | – | 10 | 3 | | | | – | – | 3 | |
| | 1,5,13,5 | – | 15 | 4 | | | | – | – | 4 | |
| Input High Voltage, V_{IH} Min. | 0,5 | – | 5 | 3,5 | | | | 3,5 | – | – | V |
| | 1 | – | 10 | 7 | | | | 7 | – | – | |
| | 1,5 | – | 15 | 11 | | | | 11 | – | – | |
| Input Current I_{IN} Max. | | 0,18 | 18 | $\pm 0,1$ | $\pm 0,1$ | ± 1 | ± 1 | – | $\pm 10^{-5}$ | $\pm 0,1$ | μ A |



3
COMMERCIAL CMOS
HIGH VOLTAGE ICs

CD4001B, CD4002B, CD4025B Types

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC | LIMITS | | UNITS |
|---|--------|------|-------|
| | MIN. | MAX. | |
| Supply-Voltage Range (For T_A = Full Package Temperature Range) | 3 | 18 | V |

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Volts referenced to V_{SS} Terminal -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} + 0.5V

DC INPUT CURRENT, ANY ONE INPUT ± 10 mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -55°C to +100°C 500mW

For T_A = +100°C to +125°C Derate Linearly at 12mW/°C to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to +125°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max +265°C

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^\circ\text{C}$; Input $t_r, t_f = 20$ ns, $C_L = 50$ pF, $R_L = 200k\Omega$

| CHARACTERISTIC | TEST CONDITIONS | ALL TYPES LIMITS | | UNITS | |
|--|-----------------|------------------|------|-------|------|
| | | V_{DD} VOLTS | TYP. | | MAX. |
| Propagation Delay Time, t_{PHL}, t_{PLH} | | 5 | 125 | 250 | ns |
| | | 10 | 60 | 120 | |
| | | 15 | 45 | 90 | |
| Transition Time, t_{THL}, t_{TLH} | | 5 | 100 | 200 | ns |
| | | 10 | 50 | 100 | |
| | | 15 | 40 | 80 | |
| Input Capacitance, C_{iN} | Any Input | | 5 | 7.5 | pF |

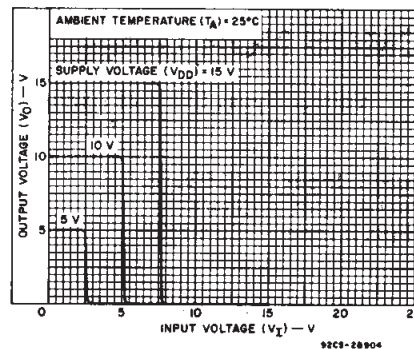


Fig. 1 - Typical voltage transfer characteristics.

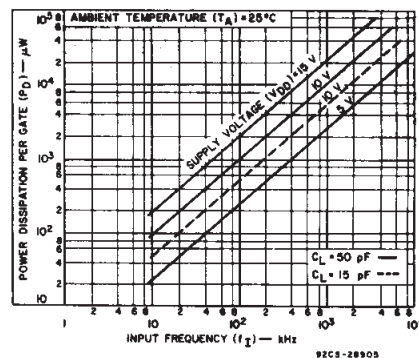


Fig. 2 - Typical power dissipation vs. frequency.

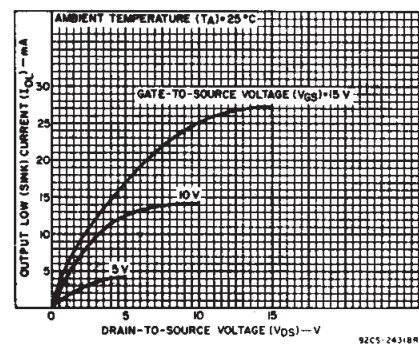


Fig. 3 - Typical output low (sink) current characteristics.

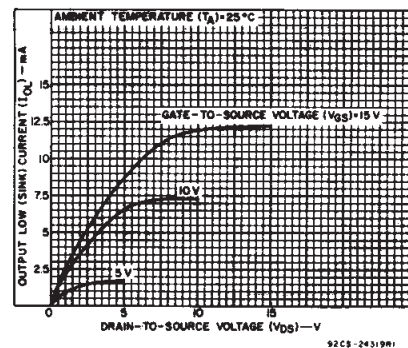


Fig. 4 - Minimum output low (sink) current characteristics.

CD4001B, CD4002B, CD4025B Types



Fig.5 - Schematic and logic diagrams for CD4001B.



Fig.6 - Schematic and logic diagrams for CD4002B.



Fig.7 - Schematic and logic diagrams for CD4025B.

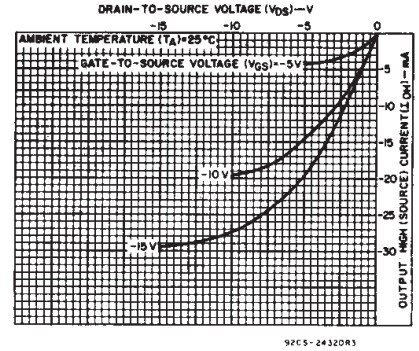


Fig.8 - Typical output high (source) current characteristics.

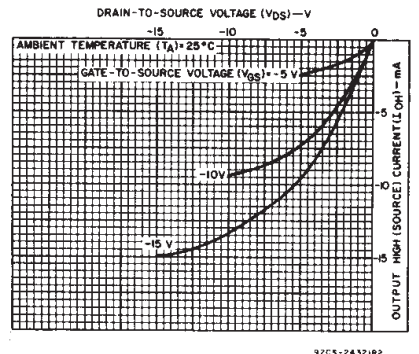


Fig.9 - Minimum output high (source) current characteristics.

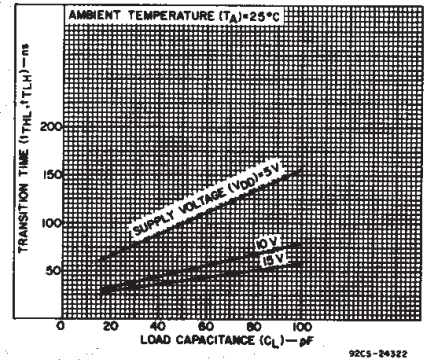


Fig.10 - Typical transition time vs. load capacitance.

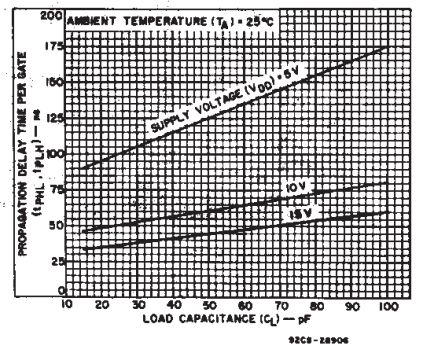


Fig.11 - Typical propagation delay time vs. load capacitance.

COMMERCIAL CMOS HIGH VOLTAGE ICs

CD4001B, CD4002B, CD4025B Types



Fig. 13 - Input leakage current test circuit.



Fig. 14 - Input-voltage test circuit.

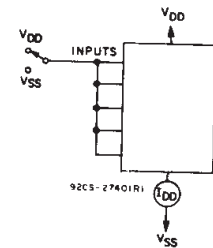
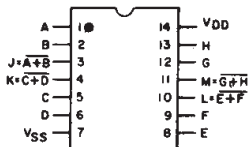
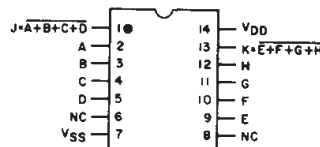


Fig. 15 - Quiescent-device current test circuit.

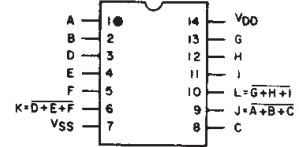
TERMINAL ASSIGNMENTS (TOP VIEW)



NC = NO CONNECTION
CD4001B

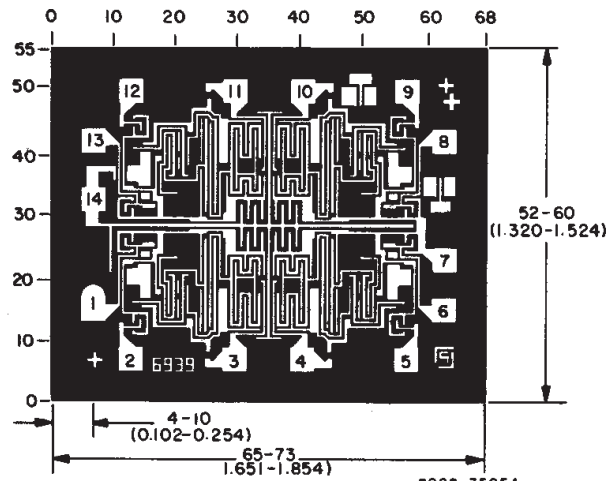


NC = NO CONNECTION
CD4002B



NC = NO CONNECTION
CD4025B

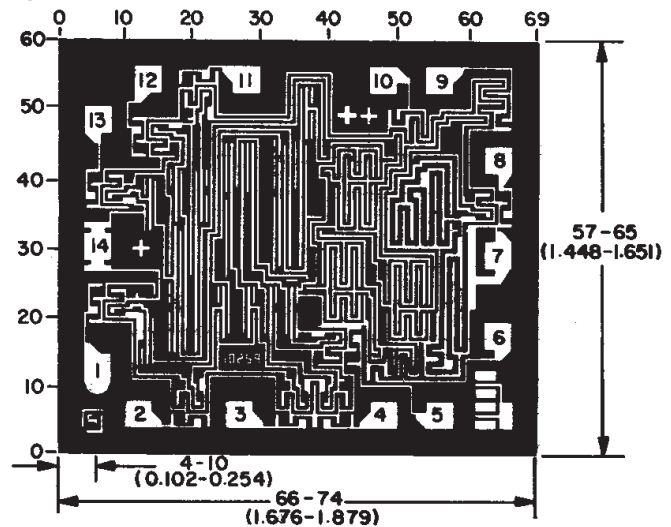
Chip Dimensions and Pad Layouts



CD4001B



CD4002B



CD4025B

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| 7704403CA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 7704403CA CD4002BF3A | Samples |
| 89263AKB3T | OBSOLETE | CFP | WR | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| CD4001BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4001BE | Samples |
| CD4001BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4001BE | Samples |
| CD4001BF | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4001BF | Samples |
| CD4001BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4001BF3A | Samples |
| CD4001BF3AS2534 | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | | | |
| CD4001BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BM96E4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BM96G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BMG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BMT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001BM | Samples |
| CD4001BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001B | Samples |
| CD4001BNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4001B | Samples |
| CD4001BPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM001B | Samples |
| CD4001BPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM001B | Samples |
| CD4001BPWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM001B | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4002BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4002BE | Samples |
| CD4002BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4002BE | Samples |
| CD4002BF | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4002BF | Samples |
| CD4002BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 7704403CA CD4002BF3A | Samples |
| CD4002BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002BM | Samples |
| CD4002BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002BM | Samples |
| CD4002BMG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002BM | Samples |
| CD4002BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002B | Samples |
| CD4002BNSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002B | Samples |
| CD4002BNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4002B | Samples |
| CD4002BPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM002B | Samples |
| CD4002BPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM002B | Samples |
| CD4002BPWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM002B | Samples |
| CD4025BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4025BE | Samples |
| CD4025BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4025BE | Samples |
| CD4025BF | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4025BF | Samples |
| CD4025BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4025BF3A | Samples |
| CD4025BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025BM | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4025BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025BM | Samples |
| CD4025BMG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025BM | Samples |
| CD4025BMT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025BM | Samples |
| CD4025BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025B | Samples |
| CD4025BNSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4025B | Samples |
| CD4025BPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM025B | Samples |
| CD4025BPWE4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM025B | Samples |
| JM38510/05252BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05252BCA | Samples |
| JM38510/05254BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05254BCA | Samples |
| M38510/05252BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05252BCA | Samples |
| M38510/05254BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05254BCA | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4001B, CD4001B-MIL, CD4002B, CD4002B-MIL, CD4025B, CD4025B-MIL :

● Catalog: [CD4001B](#), [CD4002B](#), [CD4025B](#)

● Military: [CD4001B-MIL](#), [CD4002B-MIL](#), [CD4025B-MIL](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4001BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4001BMT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4001BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4001BPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4002BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4002BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4002BPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4025BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4025BMT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4025BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

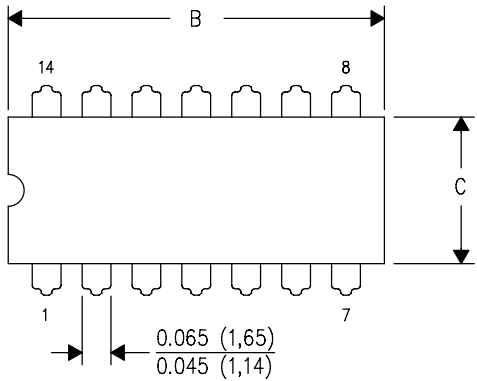
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

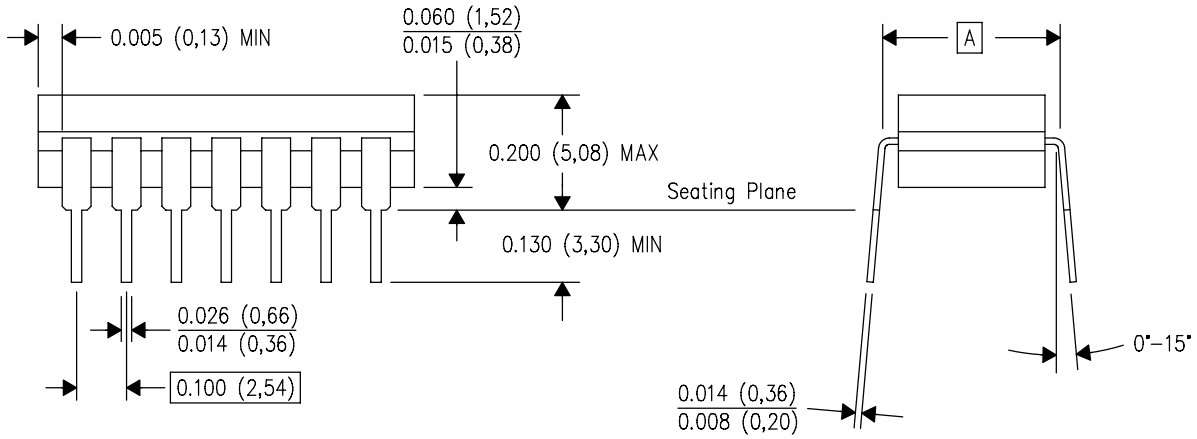
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4001BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4001BMT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| CD4001BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4001BPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| CD4002BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4002BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4002BPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| CD4025BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4025BMT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| CD4025BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

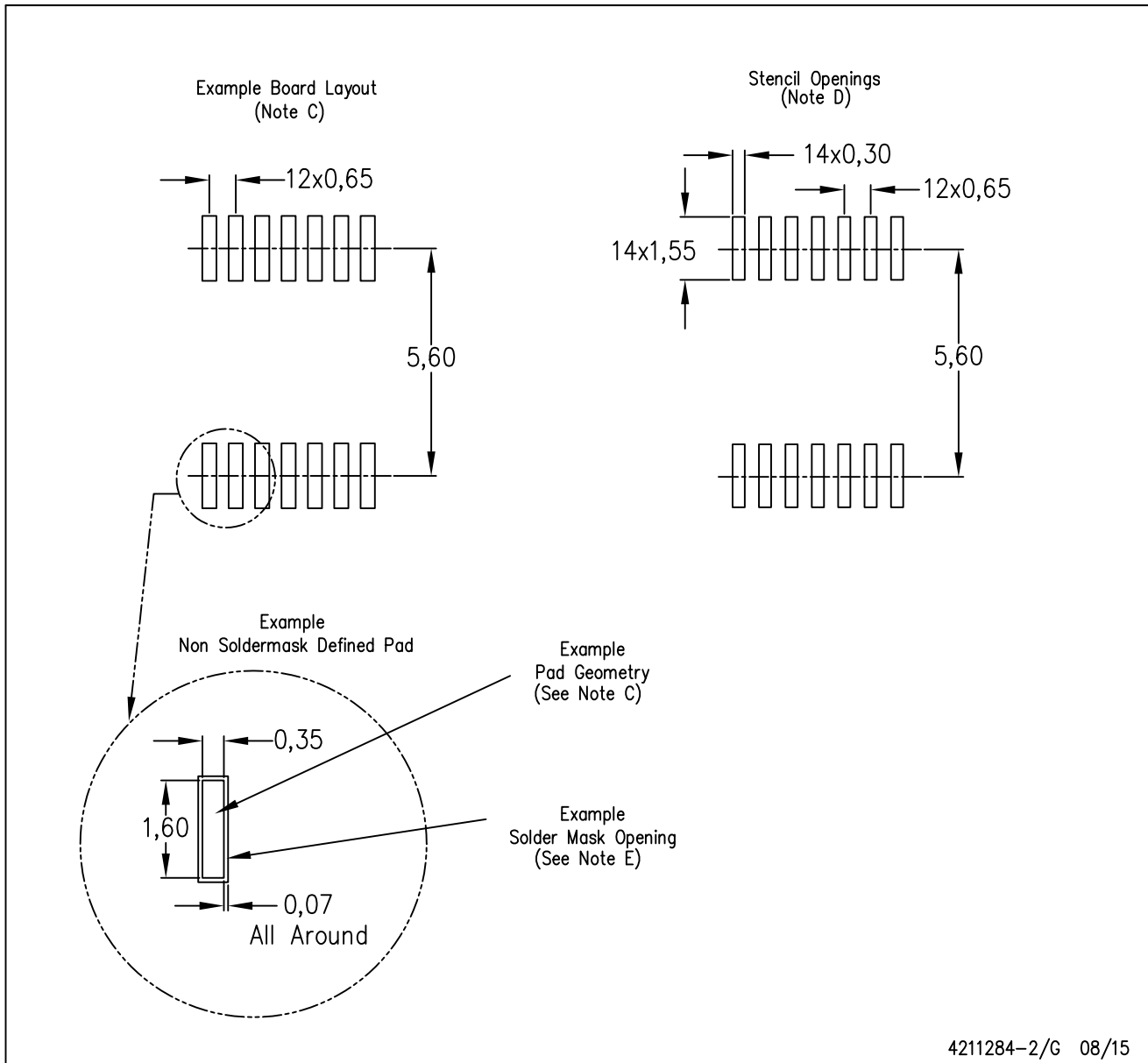


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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